L Number	Hits	Search Text	DB	Time stamp
1	4416	ion adj beam adj etch\$3	USPAT;	2004/02/27 10:53
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	472	(ion adj beam adj etch\$3) and focus\$3 near	USPAT;	2004/02/27 12:10
		ion adj beam	US-PGPUB;	, ,
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	128	((ion adj beam adj etch\$3) and focus\$3 near	USPAT;	2004/02/27 10:55
		ion adj beam) and (etch\$3 remov\$3 strip\$4)	US-PGPUB;	,,
		near (resist photoresist organic metal\$3	EPO; JPO;	
		conduct\$3)	DERWENT;	
		- conductys,	IBM TDB	
4	92	((ion adj beam adj etch\$3) and focus\$3 near	USPAT;	2004/02/27 10:56
	) <u>, , , , , , , , , , , , , , , , , , ,</u>	ion adj beam) and (etch\$3 remov\$3 strip\$4)	US-PGPUB;	2004/02/27 10:30
		adj (resist photoresist organic metal\$3	EPO; JPO;	1
		conduct\$3)	DERWENT;	
			IBM TDB	
5	22	(((ion adj beam adj etch\$3) and focus\$3 near	USPAT;	2004/02/27 10:56
5	22	ion adj beam) and (etch\$3 remov\$3 strip\$4)	US-PGPUB;	2501,02,2, 10.30
		adj (resist photoresist organic metal\$3	EPO; JPO;	
		conduct\$3)) and (etch\$3 remov\$3 strip\$4) adj	DERWENT;	
		(resist photoresist organic metal\$3	IBM TDB	
		conduct\$3) with beam	1511_155	
6	1687	(ion adj beam adj etch\$3) and focus\$3 near	USPAT;	2004/02/27 12:12
	1007	ion adj beam FIB and etch\$3	US-PGPUB;	2004/02/27 12:12
		1011 adj beam FIB and ecchips	EPO; JPO;	
			DERWENT;	
7	1243	((focus\$3 near ion near beam) FIB) with	IBM_TDB	2004/02/27 12:12
	1243		USPAT;	2004/02/27 12:13
		etch\$3	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	İ
	3	((focus\$3 near ion near beam) FIB) with	IBM_TDB	2004/02/27 12:10
8	3		USPAT;	2004/02/27 12:18
		etch\$3 same organic adj (film layer)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	^	20010027020 HDDN	IBM_TDB	2004/02/27 12:17
9	0	20010027029.URPN.	USPAT	2004/02/27 12:17 2004/02/27 12:20
10	3	((focus\$3 near ion near beam) FIB) same	USPAT;	2004/02/2/ 12:20
		etch\$3 same organic adj (film layer)not (((focus\$3 near ion near beam) FIB) with	US-PGPUB;	
			EPO; JPO;	
		etch\$3 same organic adj (film layer))	DERWENT;	
11	36	(/foguation none boom) ETD\ com-	IBM_TDB	2004/02/27 12:42
11	26	((focus\$3 near ion near beam) FIB) same	USPAT;	2004/02/27 12:42
		etch\$3 and organic adj (film layer) not	US-PGPUB;	
1		((((focus\$3 near ion near beam) FIB) with	EPO; JPO;	[
}		etch\$3 same organic adj (film layer))	DERWENT;	
		(((focus\$3 near ion near beam) FIB) same	IBM_TDB	
		etch\$3 same organic adj (film layer) not		
		(((focus\$3 near ion near beam) FIB) with		
		etch\$3 same organic adj (film layer))))		0001100155 55
12	20	((focus\$3 near ion near beam) FIB) and	USPAT;	2004/02/27 12:42
		conduct\$4 near organic	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
0.40		. W.S.	IBM_TDB	